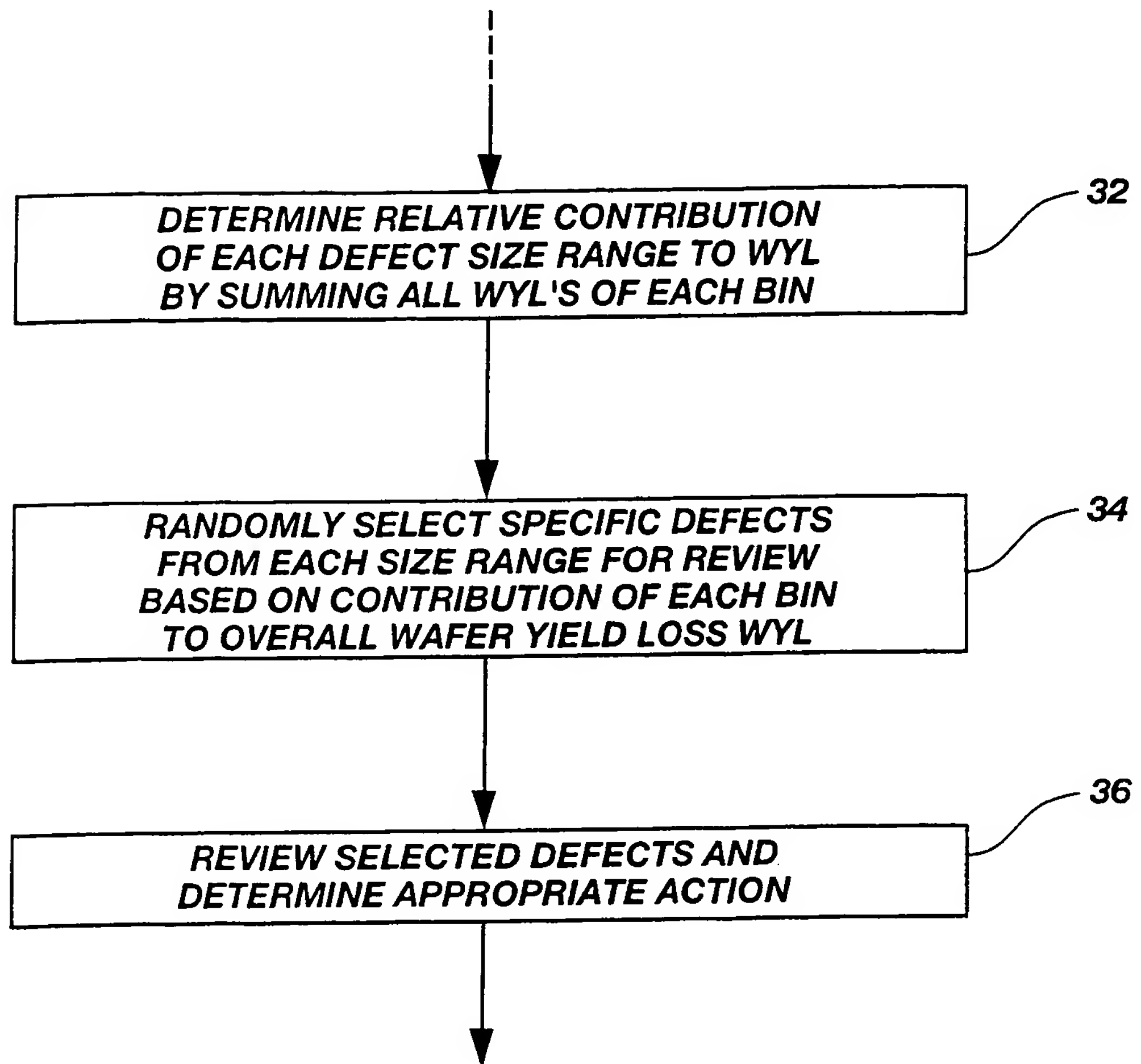
**Fig. 2A**

**Fig. 2B**

Lot No.  
Wager No.  
Date  
Inspection Level

Bin No.	Defect Size	# Defects	% of Total	WYL	D	P	S
1	0.0-0.5 $\mu$ m	7	2.9	39.4	0.005	0.005	0
2	0.5-1.0 $\mu$ m	111	46.6	34.0	0.141	0.153	2
3	1.0-2.0 $\mu$ m	81	34.0	31.7	0.199	0.216	3
4	2.0-4.0 $\mu$ m	2	0.8	38.6	0.025	0.027	0
5	4.0-8.0 $\mu$ m	26	10.9	23.6	0.404	0.439	5
6	> 8.0 $\mu$ m	11	4.6	33.8	0.146	0.159	2
Total		238	100.0	39.6	0.920	1.000	12

Fig. 3

DEFECT REVIEW SHEET

PART TYPE:  
LOT NO:  
WAFER ID:  
STEP ID:  
TOOL ID:  
PROJECT NO:

DATE:

# DEFECTS SAMPLED:  
OPERATOR:  
TIME IN:  
TIME OUT:

PREDICTED WAFER YIELD LOSS WYL + 39.6  
TOTAL DEFECT COUNT = 238

BIN #	1			2			3			4			5			6		
SIZE	0.0-0.5			0.5-1.0			1.0-2.0			2.0-4.0			4.0-8.0			> 8.0		
WYL	39.4			34.0			31.7			38.6			23.6			33.8		
# DEFECTS	7			111			81			2			26			11		
	ID P			ID P			ID P			ID P			ID P			ID P		
				183	2	✓	64	2	✓				13	1	✓	162	1	✓
				213	2	✓	205	2	✓				83	1	✓	192	1	✓
							226	2	✓				194	1	✓			
													206	2	✓			
													225	2	✓			

EXTRA SAMPLES		
DIE	DEFECT ID	DESCRIPTION

DEFECT TYPE	DESCRIPTION	TOTAL
1	Block etch	5
2	Lower Level Contamination	7
3		
4		
5		
6	CANNOT FIND	

Fig. 4